AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (currently amended) A circuit board connector formed by cutting a conductive plate material provided with plating layers on front and back sides thereof, said circuit board connector comprising:

a main body portion;

a first connecting portion bent at a right angle to said main body portion for connection to a first circuit board; [[and]]

a second connecting portion for connection to a terminal connecting socket of a second circuit board, the second connecting portion being positioned in the terminal connecting socket[[,]]; and

an auxiliary connecting portion formed from a portion of the main body portion and bent so as to be parallel to said first connecting portion, thereby leaving an opening in the main body portion,

wherein the second connecting portion of the circuit board connector is formed into a shape having an annular transverse cross section in such a manner that cut surfaces at both edges of the second connecting portion oppose each other, so that one of the plating layers may form an

outer circumferential surface of the second connecting portion and be connected to the terminal connecting socket, and

wherein each of said plating layers is formed from one of gold, silver, copper, nickel, palladium and tin.

Claim 2 (canceled).

Claim 3 (previously presented) The circuit board connector according to claim 1, wherein a gap is provided between the cut surfaces at both edges of the second connecting portion that oppose each other.

Claim 4 (previously presented) The circuit board connector according to claim 3, wherein a lead portion is provided between the main portion and the second connecting portion, and the lead portion is subjected to a bending process for reinforcement.

Claim 5 (previously presented) The circuit board connector according to claim 4, wherein in the bending process the lead portion is formed to have an O-shaped or C-shaped transverse cross section.

Claim 6 (currently amended) A circuit board connector, comprising a first connecting portion bent at a right angle to a main body portion of said connector for connection to a first circuit board and a second connecting portion connected to a second circuit board,

wherein the circuit board connector is obtained by cutting a conductive plate material provided with plating layers on front and back sides, and thereafter forming the second connecting portion so as to have an annular transverse cross section and bending the second connecting portion so that cut surfaces are located inside the annular cross-sectional shape,

wherein an auxiliary connecting portion is formed from a portion of said main body portion and is bent so as to be parallel to said first connecting portion, and

wherein each of said plating layers is formed from one of gold, silver, copper, nickel, palladium and tin.

Claim 7 (previously presented) The circuit board connector according to claim 6, wherein the circuit board connector comprises a lead portion between the main body portion and the second connecting portion, and the lead portion is subjected to a bending process.

Claim 8 (previously presented) The circuit board connector according to claim 7, wherein in the bending process the lead portion is formed to have an O-shaped or C-shaped transverse cross section.

Claim 9 (previously presented) A method of manufacturing an electronic apparatus, comprising: mounting an electronic device furnished with a first circuit board to which the first connecting portion of the circuit board connector according to claim 1 is connected, uprightly onto a second circuit substrate arranged in the electronic apparatus.

Claim 10 (previously presented) A method of manufacturing an electronic apparatus, comprising: mounting an electronic device furnished with a first circuit board to which the first connecting portion of the circuit board connector according to claim 6 is connected, uprightly onto a second circuit substrate arranged in the electronic apparatus.